

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4892658

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DIODES FABTECH, INC.	03/29/2018
RECEIVING PARTY DATA	
Name:	DIODES INCORPORATED
Street Address:	4949 HEDGCOXE ROAD
Internal Address:	SUITE 200
City:	PLANO
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 11	
Property Type	Number
Patent Number:	8426971
Patent Number:	7847315
Patent Number:	7709864
Patent Number:	6797992
Patent Number:	6717229
Patent Number:	6462393
Patent Number:	6376346
Patent Number:	6362112
Application Number:	10718827
Application Number:	10158453
Application Number:	09506420
CORRESPONDENCE DATA	
Fax Number:	(213)620-1398
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2136201780
Email:	ktuszynski@sheppardmullin.com
Correspondent Name:	SHEPPARD MULLIN RICHTER & HAMPTON LLP
Address Line 1:	333 S. HOPE STREET
Address Line 2:	43RD FLOOR

PATENT

Address Line 4: LOS ANGELES, CALIFORNIA 90071	
ATTORNEY DOCKET NUMBER:	0WYK-242551
NAME OF SUBMITTER:	DARREN M. FRANKLIN
SIGNATURE:	/Darren M. Franklin/
DATE SIGNED:	03/30/2018
Total Attachments: 4 source=Diodes FabTech Inc. to Diodes Incorporated Assignment#page1.tif source=Diodes FabTech Inc. to Diodes Incorporated Assignment#page2.tif source=Diodes FabTech Inc. to Diodes Incorporated Assignment#page3.tif source=Diodes FabTech Inc. to Diodes Incorporated Assignment#page4.tif	

PATENT ASSIGNMENT

THIS PATENT ASSIGNMENT ("Assignment") is executed this March 29, 2018, by and between Diodes FabTech Inc., a Delaware corporation ("Assignor"), and Diodes Incorporated, a Delaware corporation ("Assignee"), and shall be effective March 31, 2018, at 11:59 p.m. Eastern time.

WHEREAS, Assignor owns all of the patents and patent applications identified in Schedule A hereto, together with the inventions described or claimed therein (collectively, the "Assigned Patents");

WHEREAS, Assignor is scheduled to be merged with and into Assignee on March 31, 2018, at 11:59 p.m. Eastern time (the "Merger");

WHEREAS, upon the effectiveness of the Merger, Assignee will possess all of the estate, property, rights, privileges, and franchises of Assignor, including the Assigned Patents;

WHEREAS, Assignor desires to assign to Assignee all right, title, and interest of Assignor in and to the Assigned Patents, and Assignee desires to accept such assignment; and

WHEREAS, Assignor and Assignee accordingly wish to execute this recordable instrument, assigning all of Assignor's right, title and interest in and to the Assigned Patents to Assignee.

NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Assignor and Assignee agree as follows:

1. Assignor does hereby, effective March 31, 2018 at 11:59 p.m. Eastern time, irrevocably sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title and interest throughout the world in, to and under the Assigned Patents, and the inventions disclosed therein, and all divisions, renewals and continuations thereof; and all Letters Patent which may be granted thereon and all reissues and extensions thereof, all applications for Letters Patent which have been filed claiming priority to the Assigned Patents in any country, and all Letters Patent which have been or may hereafter be granted for said patents in any country; and all rights of priority under the Paris Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and all income, royalties, license fees and payments now or hereafter due or payable with respect thereto, as well as all rights to any actions, causes of action, and rights to recover damages and payments for past, present, or future infringements or misappropriations thereof.

2. Assignor hereby authorizes and requests the Commissioner of Patents of the United States and any official of any country or countries foreign to the United States, whose duty it is to issue patents, to record Assignee as the assignee and owner of the Patents and to issue all Letters Patent to the Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument. The parties shall cooperate and execute such further documents that are reasonable, convenient, necessary, or desirable to carry out the provisions of this Assignment. Assignor will, at Assignee's request, execute, acknowledge,

deliver and/or record such other assignments or any other instruments as Assignee may deem necessary to evidence, enforce, or defend its rights under this Assignment.

3. Assignor represents and warrants that (i) it has full power and authority to enter into this Assignment; (ii) it will be bound by and perform its obligations under this Assignment; (iii) this Assignment, when signed and delivered by Assignor, will be duly and validly executed and delivered and will be the valid and binding obligation of Assignor, enforceable against Assignor in accordance with its terms; (iv) Assignor has the exclusive authority to enter into this Assignment and transfer, assign, sell, and convey the Assigned Patents; and (v) the Assigned Patents are free of any claims, liens or encumbrances of any third party, with the exception of a security interest in the Assigned Patents in favor of Bank of America, N.A., as Administrative Agent (the "Administrative Agent"); and (vi) this Assignment is permitted pursuant to the agreements governing such security interest in favor of the Administrative Agent.

4. The parties hereby irrevocably submit to the non-exclusive jurisdiction of any federal or state court located within the State of California over any dispute arising out of or relating to this Assignment or any of the obligations contemplated hereby, and each party hereby irrevocably agrees that all claims in respect of such dispute or any suit, action, or proceeding related thereto may be heard and determined in such courts. The parties irrevocably waive, to the fullest extent permitted by applicable law, any objection which they may now or later have to the laying of venue of any such dispute brought in such court or any defense of inconvenient forum for the maintenance of such dispute. Each of the parties agrees that a judgment in any such dispute may be enforced in other jurisdictions by suit on the judgment or in any other manner provided by law.

5. This Assignment may be executed in two or more counterparts, each of which shall be deemed an original, but all of which together shall constitute one and the same instrument.

IN WITNESS WHEREOF, the parties hereto have duly executed under seal and delivered this Agreement as of the day and year first above written.

ASSIGNOR:

Diodes FabTech Inc.

ASSIGNEE:

Diodes Incorporated

By: Richard D White

Name: Richard Dallas White

Title: CFO & Secretary

By: Richard D White

Name: Richard Dallas White

Title: CFO & Secretary

SCHEDULE A**ASSIGNED PATENTS**

Title	Patent/Appl. No.	Issue/Filing Date	Inventor(s)
TOP TRI-METAL SYSTEM FOR SILICON POWER SEMICONDUCTOR DEVICES	8,426,971	04/23/2013	Roman Hamerski
HIGH EFFICIENCY RECTIFIER	7,847,315	12/07/2010	Roman J. Hamerski Zerui Chen James Man-Fai Hong Johnny Duc Van Chiem Christopher D. Hruska Timothy Eastman
HIGH-EFFICIENCY SCHOTTKY RECTIFIER AND METHOD OF MANUFACTURING SAME	7,709,864	05/04/2010	Roman Hamerski Chris Hruska Fazia Hossain
APPARATUS AND METHOD FOR FABRICATING A HIGH REVERSE VOLTAGE SEMICONDUCTOR DEVICE	6,797,992	09/28/2004	Roman J. Hamerski Walter R. Buchanan
DISTRIBUTED REVERSE SURGE GUARD	6,717,229	04/06/2004	Walter R. Buchanan Roman J. Hamerski Wayne A. Smith
SCHOTTKY DEVICE	6,462,393	10/08/2002	Walter R. Buchanan Roman J. Hamerski
HIGH VOLTAGE DEVICE AND METHOD FOR MAKING THE SAME	6,376,346	04/23/2002	Walter R. Buchanan Roman J. Hamerski
SINGLE STEP ETCHED MOAT	6,362,112	03/26/2002	Roman J. Hamerski

Schedule A

Title	Patent/Appl. No.	Issue/Filing Date	Inventor(s)
HIGH VOLTAGE SEMICONDUCTOR DEVICE HAVING CURRENT LOCALIZATION REGION	10/718,827	11/21/2003	Roman J. Hamerski Walter R. Buchanan
NOISE REDUCTION IN SEMICONDUCTOR DEVICES UTILIZING CARRIER CONTROLLING SUBSTANCES	10/158,453	05/30/2002	Roman J. Hamerski
DEVICE WITH EPITAXIAL BASE	09/506,420	02/17/2000	Roman J. Hamerski Gary W. Gladish

Schedule A